Preferred Device

## **Triacs**

## **Silicon Bidirectional Thyristors**

Designed primarily for full-wave ac control applications, such as lighting systems, heater controls, motor controls and power supplies; or wherever full-wave silicon-gate-controlled devices are needed.

- Off-State Voltages to 800 Volts
- All Diffused and Glass Passivated Junctions for Parameter Uniformity and Stability
- Small, Rugged Thermowatt Construction for Thermal Resistance and High Heat Dissipation
- Gate Triggering Guaranteed in Four Modes
- **%** Indicates UL Registered File #E69369
- Device Marking: Logo, Device Type, e.g., MAC223A6FP, Date Code

## MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

| Rating  | Symbol                                 | Value             | Unit             |
|---|--|-------------------|------------------|
| Peak Repetitive Off-State Voltage <sup>(1)</sup> (T <sub>J</sub> = -40 to +125°C, Sine Wave 50 to 60 Hz, Gate Open)           | V <sub>DRM</sub> ,<br>V <sub>RRM</sub> |                   | Volts            |
| MAC223A6FP<br>MAC223A8FP<br>MAC223A10FP   |  | 400<br>600<br>800 | (5)              |
| On-State RMS Current (T <sub>C</sub> = +80°C) <sup>(2)</sup> Full Cycle Sine Wave 50 to 60 Hz                                 | I <sub>T(RMS)</sub>                    | 25                | Amps             |
| Peak Non-repetitive Surge Current<br>(One Full Cycle, 60 Hz, T <sub>C</sub> = 80°C)<br>Preceded and followed by rated current | I <sub>TSM</sub>                       | 250               | Amps             |
| Circuit Fusing (t = 8.3 ms)   | l <sup>2</sup> t                       | 260               | A <sup>2</sup> s |
| Peak Gate Power<br>(t $\leq$ 2 µsec; T <sub>C</sub> = +80°C)  | Р <sub>GМ</sub>                        | 20                | Watts            |
| Average Gate Power<br>(t = 8.3 ms; T <sub>C</sub> = +80°C)  | P <sub>G(AV)</sub>                     | 0.5               | Watt             |
| Peak Gate Current<br>(t ≤ 2 μsec; T <sub>C</sub> = +80°C)   | I <sub>GM</sub>                        | 2.0               | Amps             |
| Peak Gate Voltage<br>(t ≤ 2 μsec; T <sub>C</sub> = +80°C)   | V <sub>GM</sub>                        | ±10               | Volts            |
| RMS Isolation Voltage (T <sub>A</sub> = 25°C,<br>Relative Humidity ≤ 20%) (%)   | V <sub>(ISO)</sub>                     | 1500              | Volts            |
| Operating Junction Temperature  | TJ                                     | -40 to<br>+125    | °C               |
| Storage Temperature Range   | T <sub>stg</sub>                       | -40 to<br>+150    | °C               |
| Mounting Torque   |  | 8.0               | in. lb.          |

- (1) V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.
- (2) The case temperature reference point for all  $T_{\rm C}$  measurements is a point on the center lead of the package as close as possible to the plastic body.



### ON Semiconductor

http://onsemi.com

## ISOLATED TRIAC (%) 25 AMPERES RMS 400 thru 800 VOLTS





ISOLATED TO-220 Full Pack CASE 221C STYLE 3

| PIN ASSIGNMENT |                 |  |
|----------------|-----------------|--|
| 1              | Main Terminal 1 |  |
| 2              | Main Terminal 2 |  |
| 3              | Gate            |  |

#### **ORDERING INFORMATION**

| Device      | Package          | Shipping |
|-------------|------------------|----------|
| MAC223A6FP  | ISOLATED TO220FP | 500/Box  |
| MAC223A8FP  | ISOLATED TO220FP | 500/Box  |
| MAC223A10FP | ISOLATED TO220FP | 500/Box  |

**Preferred** devices are recommended choices for future use and best overall value.

## THERMAL CHARACTERISTICS

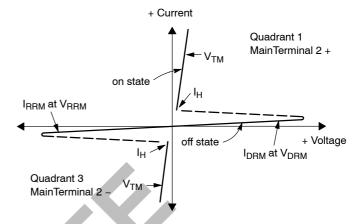
| Characteristic  | Symbol          | Max | Unit |
|---|-----------------|-----|------|
| Thermal Resistance, Junction to Case  | $R_{	heta JC}$  | 1.2 | °C/W |
| Thermal Resistance, Case to Sink  | $R_{\theta CS}$ | 2.2 | °C/W |
| Thermal Resistance, Junction to Ambient                                       | $R_{\theta JA}$ | 60  | °C/W |
| Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds | T <sub>L</sub>  | 260 | °C   |

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted: Electricals apply in both directions)

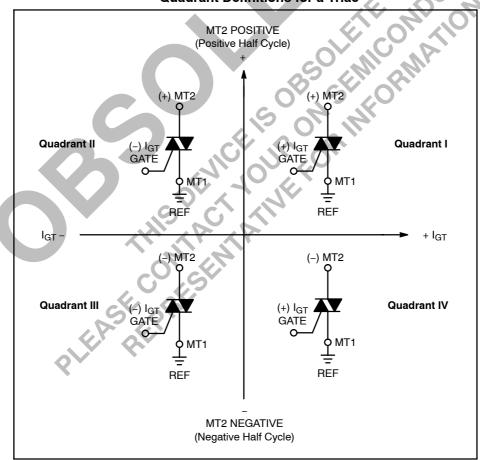
| Characteristic  | Symbol          | Min    | Тур        | Max        | Unit     |
|---|-----------------|--------|------------|------------|----------|
| OFF CHARACTERISTICS   |                 | •      |            |            |          |
| $ \begin{array}{ll} \text{Peak Repetitive Blocking Current} & T_J = 29 \\ \text{(V}_D = \text{Rated V}_{DRM}, \text{V}_{RRM}; \text{Gate Open)} & T_J = 12 \\ \end{array} $ |                 | _<br>_ |            | 10<br>2.0  | μA<br>mA |
| ON CHARACTERISTICS  |                 |        |            |            |          |
| Peak On-State Voltage ( $I_{TM} = \pm 35$ A Peak, Pulse Width $\leqslant$ 2 ms; Duty Cycle $\leqslant$ 2%)  | V <sub>TM</sub> | _      | 1.4        | 1.85       | Volts    |
| Gate Trigger Current (Continuous dc) $ (V_D = 12 \ V, \ R_L = 100 \ \Omega) \\ MT2(+), \ G(+); \ MT2(-), \ G(-); \ MT2(+), \ G(-) \\ MT2(-), \ G(+) $                       | let             |        | 20<br>30   | 50<br>75   | mA       |
| Gate Trigger Voltage (Continuous dc) $(V_D=12\ V,\ R_L=100\ \Omega)\\ MT2(+),\ G(+);\ MT2(-),\ G(-);\ MT2(+),\ G(-)\\ MT2(-),\ G(+)$  | V <sub>GT</sub> |        | 1.1<br>1.3 | 2.0<br>2.5 | Volts    |
| Gate Non-trigger Voltage ( $V_D$ = 12 V, $T_J$ = 125°C, $R_L$ = 100 $\Omega$ ) All Quadrants  | V <sub>GD</sub> | 0.2    | 0.4        | _          | Volts    |
| Holding Current ( $V_D = 12 \text{ Vdc}$ , Gate Open, Initiating Current = $\pm 200 \text{ mA}$ )   | Щ               | _      | 10         | 50         | mA       |
| Gate Controlled Turn-On Time<br>(V <sub>D</sub> = Rated V <sub>DRM</sub> , I <sub>TM</sub> = 35 A Peak, I <sub>G</sub> = 200 mA)  | t <sub>gt</sub> | _      | 1.5        | _          | μs       |
| DYNAMIC CHARACTERISTICS   |                 |        |            |            |          |
| Critical Rate of Rise of Off–State Voltage $(V_D = Rated V_{DRM}, Exponential Waveform, T_C = 125°C)$   | dv/dt           | _      | 40         | _          | V/μs     |
| Critical Rate of Rise of Commutation Voltage $(V_D = Rated\ V_{DRM},\ I_{TM} = 35\ A\ Peak,\ Commutating\ di/dt = 12.6\ A/ms,\ Gate\ Unenergized,\ T_C = 80^{\circ}C)$      | dv/dt(c)        | _      | 5.0        | _          | V/μs     |
| PILLASE PREPARE   |                 |        |            |            |          |

## Voltage Current Characteristic of Triacs (Bidirectional Device)

|                  | _   |
|------------------|---|
| Symbol           | Parameter                                 |
| $V_{DRM}$        | Peak Repetitive Forward Off State Voltage |
| I <sub>DRM</sub> | Peak Forward Blocking Current             |
| V <sub>RRM</sub> | Peak Repetitive Reverse Off State Voltage |
| I <sub>RRM</sub> | Peak Reverse Blocking Current             |
| V <sub>TM</sub>  | Maximum On State Voltage                  |
| I <sub>H</sub>   | Holding Current                           |



## **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

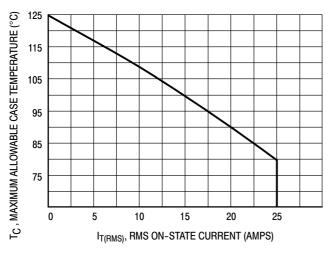


Figure 1. RMS Current Derating

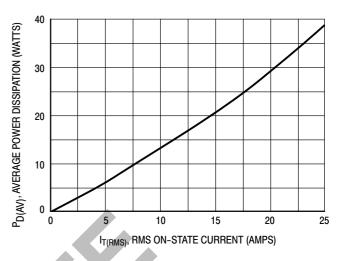
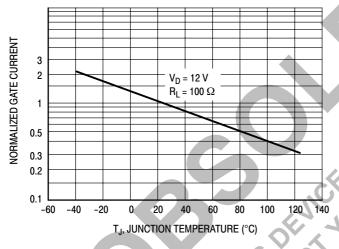


Figure 2. On-State Power Dissipation



**Figure 3. Typical Gate Trigger Current** 

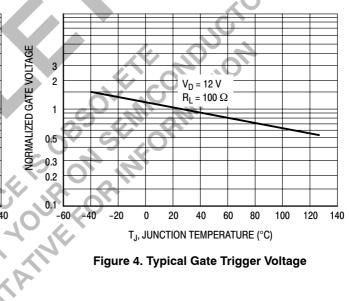


Figure 4. Typical Gate Trigger Voltage

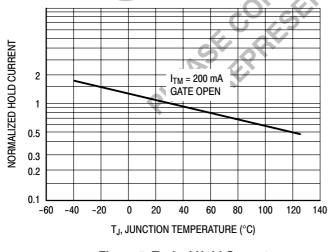


Figure 5. Typical Hold Current

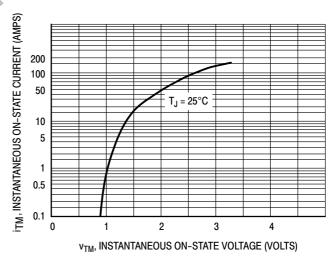
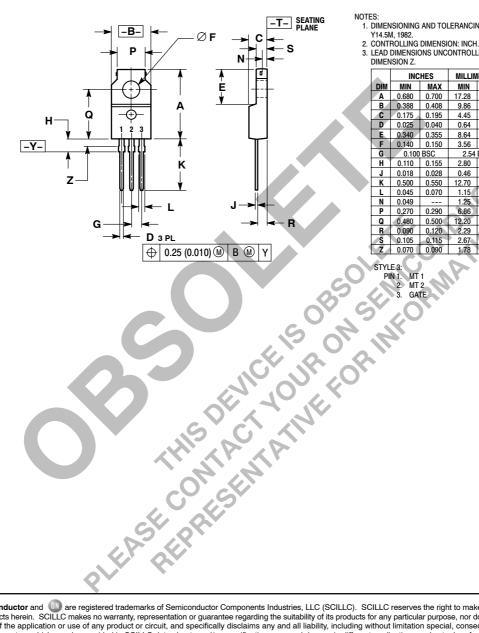


Figure 6. Typical On-State Characteristics

#### PACKAGE DIMENSIONS

#### ISOLATED TO-220 Full Pack

CASE 221C-02 **ISSUE C** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. LEAD DIMENSIONS UNCONTROLLED WITHIN DIMENSION Z.

|     | INCHES |           | MILLIMETERS |       |
|-----|--------|-----------|-------------|-------|
| DIM | MIN    | MAX       | MIN         | MAX   |
| Α   | 0.680  | 0.700     | 17.28       | 17.78 |
| В   | 0.388  | 0.408     | 9.86        | 10.36 |
| C   | 0.175  | 0.195     | 4.45        | 4.95  |
| D   | 0.025  | 0.040     | 0.64        | 1.01  |
| E   | 0.340  | 0.355     | 8.64        | 9.01  |
| F   | 0.140  | 0.150     | 3.56        | 3.81  |
| G   | 0.100  | 0.100 BSC |             | BSC   |
| H   | 0.110  | 0.155     | 2.80        | 3.93  |
| J   | 0.018  | 0.028     | 0.46        | 0.71  |
| K   | 0.500  | 0.550     | 12.70       | 13.97 |
| L   | 0.045  | 0.070     | 1.15        | 1.77  |
| N   | 0.049  |           | 1.25        |       |
| P   | 0.270  | 0.290     | 6.86        | 7.36  |
| Q   | 0.480  | 0.500     | 12.20       | 12.70 |
| R   | 0.090  | 0.120     | 2.29        | 3.04  |
| S   | 0.105  | 0.115     | 2.67        | 2.92  |
| Z   | 0.070  | 0.090     | 1.78        | 2.28  |

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